EPA–M2CTI Heat Dissipation Aluminum Base CCL

Features:

- Halogen-free, complied with ROHS and REACH requirements.
- High thermal conductivity aluminum copper clad laminate thus effectively increasing the life of electronic products.
- Without fibre-glass,but ceramic base dielectric layer.
- Good mechinability.
- Excellent dimensional stability.
- Electromagnetic compatibility.

Application areas:

- Substrate electric car, LED Backlight, Indoor/Outdoor lighting, Street LED lamp, Stage LED lights .
- Inverter/converter
- Other: IC chip substrates.

AL type：1060#、1100#、3003#、5052#、6161#

AL Thickness: 0.6mm；0.8mm；1.0mm；1.2mm；1.5mm；2.0mm；3.0mm.

Copper：1oz；2oz；3oz；4oz.

Available Size：500×600mm；600×1000mm；500×1200mm.Customer tailor sizes are available.

Performance

Item	Test Method	Units	Index	
Insulation thickness	IPC-TM-650 2.2.18.1	μm	100	150
Thermal Stress	IPC-TM-650 2.4.13.1	S	288℃＞120S	288℃＞120S
Peel Strength	IPC-TM-650 2.4.8.1	N/mm	1.2	1.2
Hi-pot Voltage	IPC-TM-650 2.5.6	KV(DC)	3.0	5.0
Break-down Voltage	IPC-TM-650 2.5.6	KV(AC)	4.0	6.0
CTI	IEC60112	V	＞600	＞600
Glass Transition Temperature	IPC-TM-650 2.4.25	℃	140	140
CTE(TMA)	IPC-TM-650 2.4.24	% (50～260℃)	0.50	0.50
Surface Resistance	IPC-TM-650 2.5.17.1	Ω	3.96×10^{9}	3.96×10^{9}
Volume Resistivity	IPC-TM-650 2.5.17.1	Ω·cm	1.68×10^{11}	1.68×10^{11}
Insulation Resistance	JIS6481-1996	Ω	1.46×10^{11}	1.46×10^{11}
Dielectric Constant 1MHZ	IPC-TM-650 2.5.5.9	/	≤5.6	≤5.6
Dissipation Factor 1MHZ	IPC-TM-650 2.5.5.9	/	≤0.034	≤0.034
Water Absorption	IPC-TM-650 2.6.2.1	%	＜0.5	＜0.5
Thermal Conductivity	ASTM D 5470	W/m·k	2.0	2.0
Thermal impedance	/	℃/W	0.45	0.53
Flammability	UL94	/	V-0	V-0

✧ All data are subject to change without notice

鹤山东力电子科技有限公司
HeShan DongLi Electronic Technologies Co.,Ltd
TEL:86-750-8219999 FAX:86-750-8219966
E-mail:epcb@epcb.cn Website:http://www.epcb.cn